MHCHXM®
www.jshxm.com

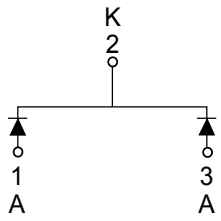
MBR30H100M
Schottky Barrier Rectifiers

■ Productor Character
- Very low profile - typical height of 1.7 mm.
- Multilayer Metal -Silicon Potential Structure.
- Low Leakage Current.
- High Current Capability, High Efficiency.
- High Junction Temperature Capability.
- RoHS Product.
- Compliance with EU REACH.

■ Summarize
- MBR30H100M Device optimized for ultra-low forward voltage drop to maximize efficiency in Power Supply applications.

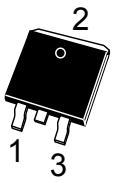
■ Primary Use
- Low Voltage High Frequency Switching Power Supply.
- Low Voltage High Frequency Invers Circuit.
- Low Voltage Continued Circuit and Protection Circuit.

■ Equivalent Circuit



RoHS

Reach



Package:TO-263M-2L
MBR30H100M
MBR30H100M-HF
HF=Halogen Free

Absolute Maximum Ratings(Ta=25°C unless otherwise noted)

Item		Symbol	Data	Unit
Maximal Inverted Repetitive Peak Voltage		V_{RRM}	100	V
Average Rectified Forward Current(Rated VR-20Khz Square Wave)-50% duty cycle	Per Device	I_{FAV}	30	A
	Per Diode		15	
Forward Peak Surge Current(Rated Load 8.3 Half Mssine Wave-According to JEDEC Method)	Per Diode	I_{FSM}	200	A
Operating Junction Temperature		T_J	-40～175	°C
Storage Temperature		T_{STG}	-40～175	°C
Typical Thermal Resistance(per leg)	Package=TO-263M-2L	$R_{\theta JC}$	2	°C/W

Electricity Character Per Diode(Ta=25°C unless otherwise noted)

Item	Test Condition	Value(min)	Value(typ)	Value(max)	Unit
V_B	Tj=25°C,IR=1mA	100	—	—	V
I_R	Tj=25°C,VR=100V	—	—	10	μA
	Tj=125°C,VR=100V	—	—	5	mA
V_F	Tj=25°C,IF=15A	—	0.82	0.86	V
	Tj=125°C,IF=15A	—	—	0.75	V
C_J	Tj=25°C,VR=4V,f=1MHz	—	370	—	pF

Typical Characteristics Curves

Fig1.Typical Forward Current and Forward Voltage

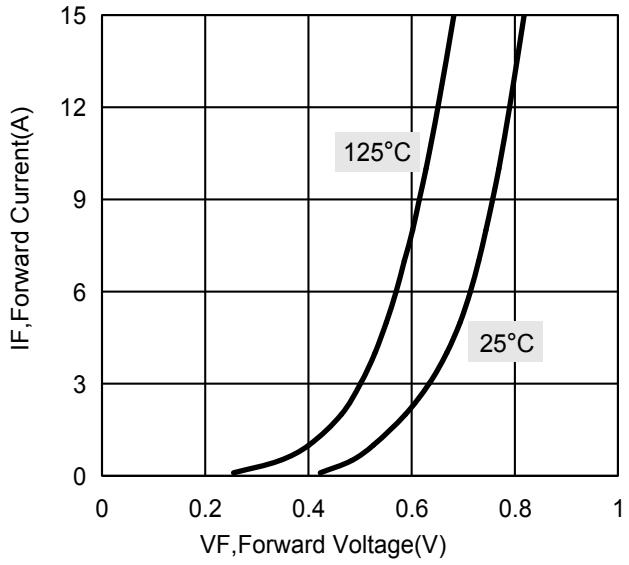


Fig2.Typical Current Derating Curve,Perelement

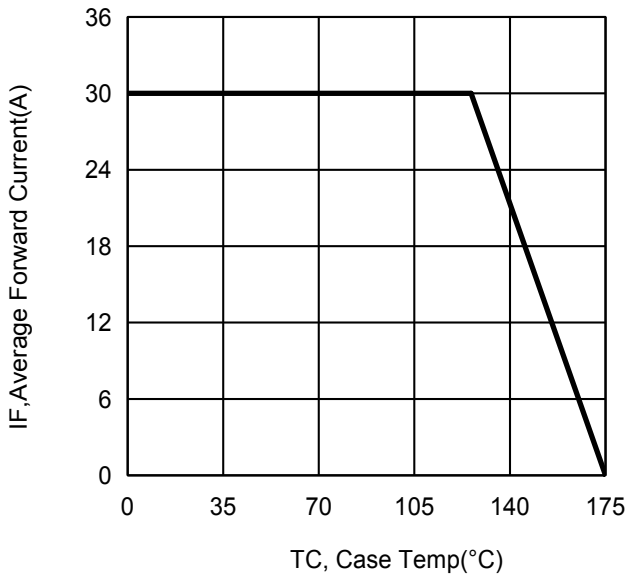


Fig3.Typical Reverse Current and Reverse Voltage

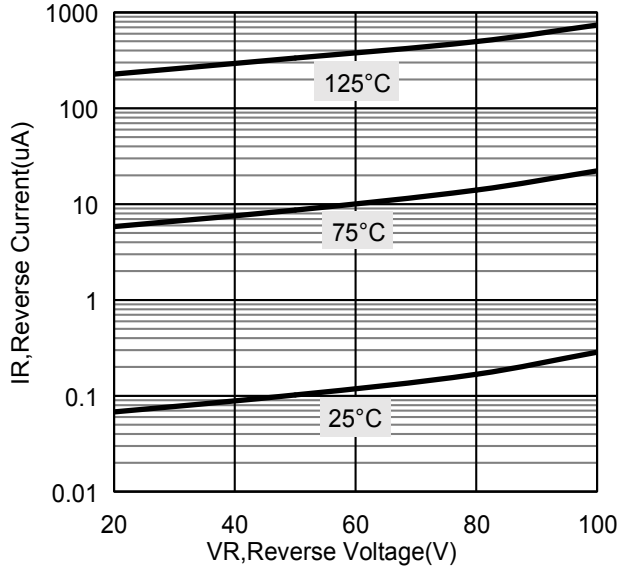
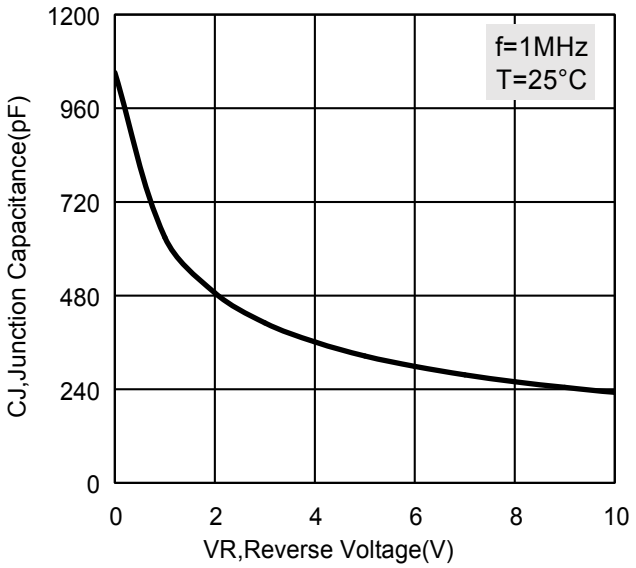
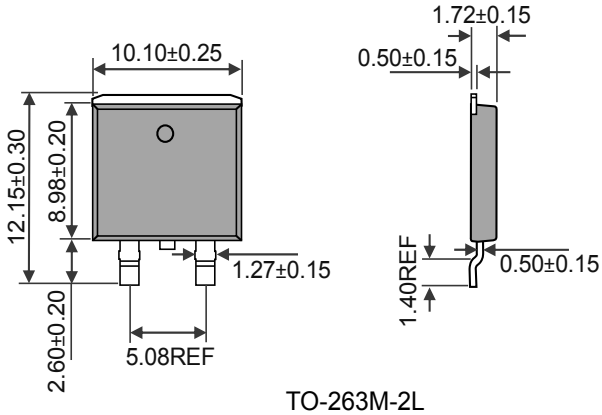


Fig4.Typical Junction Capacitance and Reverse Voltage



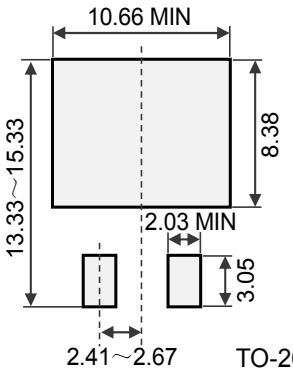
Package Outline Dimensions & Suggested Solder Pad Layout

Package Outline Dimensions



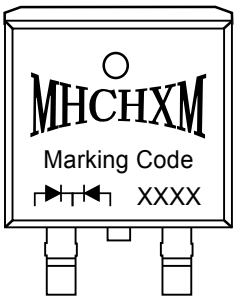
TO-263M-2L
Unit:mm

Suggested Solder Pad Layout



TO-263M-2L
Unnoted Tolerance:±0.05
Unit:mm

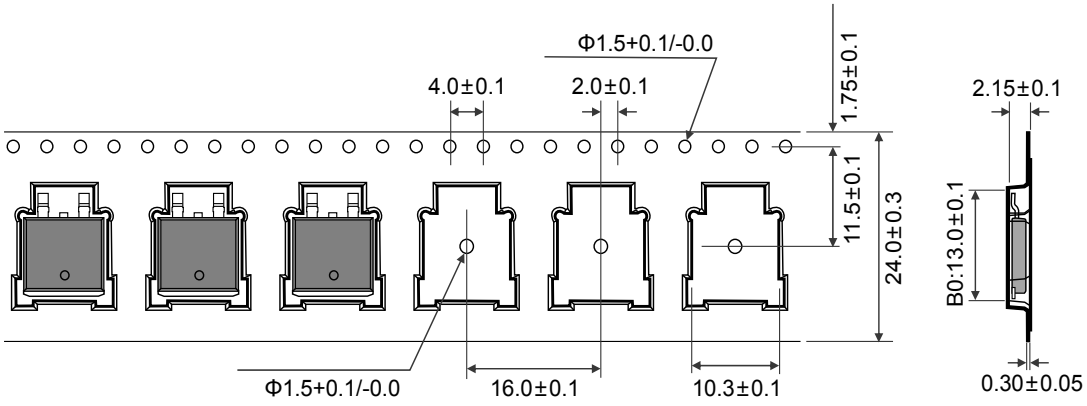
Marking Information



"MHCHXM"= Product Logo
"Marking Code"= The Following
"XXXX"= Date Code Marking

Marking Code	Part Number
MBR30H100M	MBR30H100M-HF

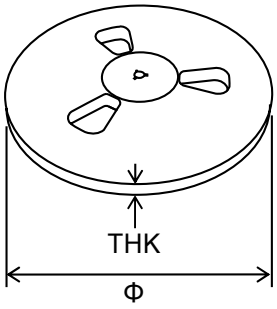
Reel Tape Dimensions (Dimensions in mm)



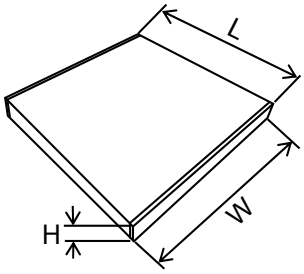
Packing Information

Packaging	Part Number	Quantity(pcs)	Size(mm)
Reel	Reel	1500	Φ330×THK25
	Inner Box	1500	L355×W335×H35
	Outer Box	15000	L385×W365×H365

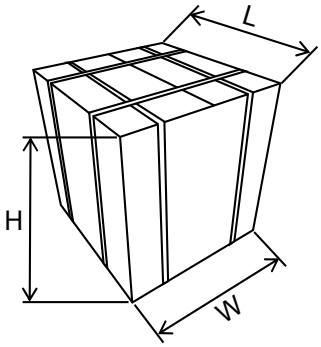
Packaging:Reel



Reel



Reel Inner Box



Reel Outer Box

Notes

Lead Forming

1.During lead frame bending, the lead frame should be bent at a distance more than 3mm from bottom of the epoxy.And the bending degree should not exceed 90°.
Note: The lead frame must be secured and do not touch the epoxy before bending to avoid damage to the transistor.In addition, when using a mold for a large number of lead molding, the structure of the fixed lead must be set, and it should be noted that the lead pressure rod structure cannot exert pressure on the epoxy resin body.

2. Do not bend the lead repeatedly. Do not bend the lead outward

Heat sink mounting

For power devices, in order to reduce junction temperature, heat dissipation blocks are usually used to disperse heat to the outside, and semiconductor power devices installed on the heat dissipation blocks can effectively dissipate heat without losing the reliability of the semiconductor, so the following matters should be noted when using:

1. Pay attention to the selection of silicone cream
In order to improve the thermal conductivity and heat dissipation effect of the device and the heat dissipation block, generally apply a thin layer of silicone grease evenly on the contact surface of the device and the heat dissipation block. Choose a silicone grease with low oil separation degree. Do not overapply it, otherwise it will attach too much stress to the resin.

2. Optimum torque is required
When using the fastening torque, pay attention not to use too much torque, so as not to damage the epoxy resin body, pay attention to the smooth cooling block body, no file chips and other foreign bodies between the transistor and the cooling block, pay attention to the selection of screws, nuts, gaskets and washers, so as not to cause damage to the transistor due to improper selection.

Soldering

1. Pay special attention to welding. When welding, the distance between the solder joint and the epoxy ball should be greater than 3mm, and it is recommended to weld it outside the tie rod base.

2. Avoid applying any pressure to the lead frame while the transistor is at high temperatures, especially when welding. Dip welding and manual welding should not be done more than once

Notes:

For specific precautions, please refer to our company's relevant technical documents or visit our official website at **http://www.jshxm.com**

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2.The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.

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